TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2-\pi$ -MOSV)

# 2SK3205

Switching Regulator Applications DC–DC Converter, and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON resistance  $: RDS (ON) = 0.36 \Omega (typ.)$
- High forward transfer admittance  $|Y_{fs}| = 4.5 \text{ S (typ.)}$
- Low leakage current  $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 150 \ V)$
- Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_D = 1 mA)$

#### Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	150	V	
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	150	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	20	A	
Drain power dissipation	n (Tc = 25°C)	PD	20	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	71	mJ	
Avalanche current		I <sub>AR</sub>	5	А	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	2	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

### **Thermal Characteristics**

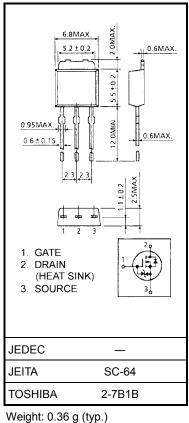
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	6.25	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	125	°C / W

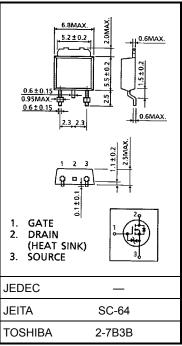
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 4.2 mH, I<sub>AR</sub> = 5 A, R<sub>G</sub> = 25  $\Omega$ ,

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.





Weight: 0.36 g (typ.)

Unit: mm

## **Electrical Characteristics (Ta = 25°C)**

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 150 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	150	_	_	V
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8		2.0	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = 4 V, I_D = 2.5 A$ $V_{GS} = 10 V, I_D = 2.5 A$		0.54	0.75	Ω
		R <sub>DS (ON)</sub>			0.36	0.5	
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	2.0	4.5	_	S
Input capacitand	ce	C <sub>iss</sub>		_	330	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	50	_	pF
Output capacitance		Coss			145	—	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int_{\mathcal{C}} I_{D} = 2.5A \\ \circ V_{OUT} \\ \circ C \\ \circ$	_	10	_	
	Turn-on time	t <sub>on</sub>		_	15	_	1
	Fall time	t <sub>f</sub>		_	10	_	ns
	Turn-off time	t <sub>off</sub>	$V_{DD} \doteq 100V$ Duty $\leq 1\%$ , t <sub>w</sub> =10µs	_	60	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	12	_	
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 120 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A		8	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			4	_	

## Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	5	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	_	_	20	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 100 A / μs	_	110	—	ns
Reverse recovery charge	Q <sub>rr</sub>		_	0.47	_	nC

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